BR® 624

Epoxy; Epoxide

Cytec Industries Inc.

Message:

BR® 624 potting compound is a one-part, low density material formulated for use in insert or edge filling of honeycomb sandwich construction. It is a thermosetting, modified epoxy system, serviceable over a temperature range of -70 to 350°F (-57 to 177°C).
BR 624 potting compound is thixotropic and cure cycles may be varied over a broad range. Cure temperatures as low as 225°F (107°C) and as high as 350°F (177°C) have been used successfully. Multiple cure cycles at temperatures up to 350°F (177°C) will not impair its use as a structural material.
Suggested Applications:
Insert and edge filling of honeycomb structures

General Information	
Features	Low Density Thixotropic
Uses	Filling Applications Structural Parts
Appearance	Maroon
Forms	Paste
Processing Method	Potting Thermoforming

Physical	Nominal Value	Unit
Specific Gravity [1]	0.650	g/cm³

NOTE	
1.	Approximate

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Recommended distributors for this material

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